

**IN THE CLAIMS:**

Please amend the claims as follows:

1. (Currently amended) An electronic part comprising:  
an external electrode; and  
a coating including a thermoplastic or thermosetting resin disposed on a surface  
of said external electrode,

wherein a conductive adhesive layer is provided on said coating and said  
conductive adhesive layer contains a conductive filler consisting of gold, silver,  
platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals, and  
wherein the thickness of said coating is less than the particle diameter of said  
conductive filler.

2. (Cancelled)

3. (Original) The electronic part as set forth in claim 1, wherein said coating  
contains a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or  
an alloy or a mixture containing these metals.

4. (Cancelled)

5. (Cancelled)

6. (Previously presented) An electronic part mounting element comprising:  
an electronic part;  
a coating containing a resin ingredient and formed on a surface of an external  
electrode of said electronic part;  
an element to be mounted with said electronic part; and  
a conductive adhesive containing a conductive filler for electrically connecting

the external electrode of said electronic part to a connecting terminal of said element to be mounted,

wherein the thickness of said coating is less than the particle diameter of said conductive filler.

7. (Original) An electronic part mounting element as set forth in claim 6, wherein said coating and said conductive adhesive are combined into one element.

8. (Original) The electronic part mounting element as set forth in claim 7, wherein a joining portion of said coating with said conductive adhesive is shaped like a fillet.

9. (Previously presented) An electronic part mounting element comprising:  
an external electrode;  
a coating of a conductive adhesive containing a conductive filler formed on the entire surface of the external electrode of the electronic part,

wherein said external electrode of said electronic part is electrically connected to a connecting terminal of an element on which said electronic part is to be mounted, said coating operative as a connecting element for connecting said external electrode to said connecting terminal,

wherein said conductive filler consists of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

10-17. (Cancelled)

18. (Currently amended) An electronic part comprising:

an external electrode;

a coating including a thermoplastic or thermosetting resin ingredient is provided

disposed on a surface of said external electrode; and

a conductive filler is disposed on said coating;

wherein the thickness of said coating is less than ~~the~~ a particle diameter of said conductive filler.

19. (Previously presented) The electronic part as set forth in claim 1, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 10.0  $\mu\text{m}$ .

20. (Previously presented) The electronic part mounting element as set forth in claim 6, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 10.0  $\mu\text{m}$ .

21. (Previously presented) The electronic part mounting element as set forth in claim 9, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 10.0  $\mu\text{m}$ .

22. (Previously presented) The electronic part as set forth in claim 18, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 10.0  $\mu\text{m}$ .

23. (Previously presented) The electronic part as set forth in claim 1, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 5.0  $\mu\text{m}$ .

24. (Previously presented) The electronic part mounting element as set forth in claim 6, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 5.0  $\mu\text{m}$ .

25. (Previously presented) The electronic part mounting element as set forth in

claim 9, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 5.0  $\mu\text{m}$ .

26. (Previously presented) The electronic part as set forth in claim 18, wherein the surface roughness (Ra) of said external electrode is in the range of 0.1  $\mu\text{m}$  to 5.0  $\mu\text{m}$ .

27. (Previously presented) The electronic part as set forth in claim 1, wherein said coating is disposed over the entire surface of said external electrode.